

### N-Channel Power MOSFET (5A, 900Volts)

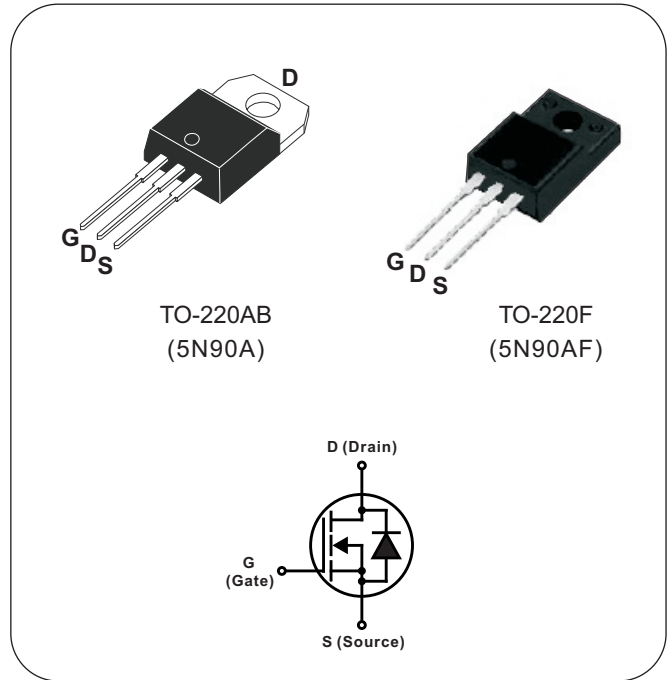
#### DESCRIPTION

The Nell **5N90** is a three-terminal silicon device with current conduction capability of 5A, fast switching speed, low on-state resistance, breakdown voltage rating of 900V, and max. threshold voltage of 5 volts.

They are designed for use in applications such as switched mode power supplies, DC to DC converters, **PWM** motor controls, bridge circuits and general purpose switching applications.

#### FEATURES

- $R_{DS(ON)} = 2.80\Omega @ V_{GS} = 10V$
- Ultra low gate charge(40nC max.)
- Low reverse transfer capacitance ( $C_{RSS} = 13pF$  typical)
- Fast switching capability
- 100% avalanche energy specified
- Improved dv/dt capability
- 150°C operation temperature



#### PRODUCT SUMMARY

$I_D$ (A)	5
$V_{DSS}$ (V)	900
$R_{DS(ON)}$ ( $\Omega$ )	2.80 @ $V_{GS} = 10V$
$Q_G$ (nC) max.	40

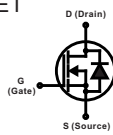
#### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ C$ unless otherwise specified)

SYMBOL	PARAMETER	TEST CONDITIONS	VALUE	UNIT	
$V_{DSS}$	Drain to Source voltage(Note 1)	$T_J=25^\circ C$ to $150^\circ C$	900	V	
$V_{DGR}$	Drain to Gate voltage	$R_{GS}=20K\Omega$	900		
$V_{GS}$	Gate to Source voltage		$\pm 30$		
$I_D$	Continuous Drain Current	$T_C=25^\circ C$	5	A	
		$T_C=100^\circ C$	3.1		
			12		
$I_{AR}$	Repetitive avalanche current (Note 1)		5	mJ	
$E_{AR}$	Repetitive avalanche energy(Note 1)	$I_{AR}=5A, R_{GS}=50\Omega, V_{GS}=10V$	5.1		
$E_{AS}$	Single pulse avalanche energy (Note 2)	$I_{AS}=5A, L=52.8mH$	660	V/ns	
dv/dt	Peak diode recovery dv/dt(Note 3)		4.0		
$P_D$	Total power dissipation (Derating factor above $25^\circ C$ )	$T_C=25^\circ C$	TO-220AB	125	W( $W/^\circ C$ )
			TO-220F	38	
$T_J$	Operation junction temperature		-55 to 150	$^\circ C$	
$T_{STG}$	Storage temperature		-55 to 150		
$T_L$	Maximum soldering temperature, for 10 seconds	1.6mm from case	300		
	Mounting torque, #6-32 or M3 screw		10 (1.1)	lbf-in (N·m)	

Note: 1.Repetitive rating: pulse width limited by junction temperature.  
 2.  $V_{DD}=50V, L=52.8mH, I_{AS}=5A, R_{GS}=25\Omega$ , starting  $T_J=25^\circ C$   
 3.  $I_{SD} \leq 5.4A, di/dt \leq 200A/\mu s, V_{DD} \leq V_{(BR)DSS}$ , starting  $T_J = 25^\circ C$ .

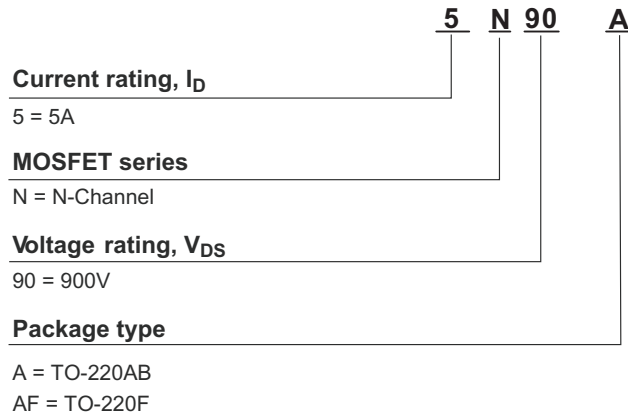
THERMAL RESISTANCE						
SYMBOL	PARAMETER		Min.	Typ.	Max.	UNIT
$R_{th(j-c)}$	Thermal resistance, junction to case	TO-220AB			1.0	°C/W
		TO-220F			3.25	
$R_{th(j-a)}$	Thermal resistance, junction to ambient	TO-220AB			62.5	
		TO-220F			62.5	

ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise specified)							
SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
◎ OFF CHARACTERISTICS							
$V_{(BR)DSS}$	Drain to source breakdown voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	900			V	
$V_{(BR)DSS}/T_J$	Breakdown voltage temperature coefficient	$I_D = 250\mu\text{A}, V_{DS} = V_{GS}$		1.0		V/°C	
$I_{DSS}$	Drain to source leakage current	$V_{DS} = 900\text{V}, V_{GS} = 0\text{V}, T_C = 25^\circ\text{C}$			10	$\mu\text{A}$	
		$V_{DS} = 720\text{V}, V_{GS} = 0\text{V}, T_C = 125^\circ\text{C}$			100		
$I_{GSS}$	Gate to source forward leakage current	$V_{GS} = 30\text{V}, V_{DS} = 0\text{V}$			100	nA	
	Gate to source reverse leakage current	$V_{GS} = -30\text{V}, V_{DS} = 0\text{V}$			-100		
◎ ON CHARACTERISTICS							
$R_{DS(ON)}$	Static drain to source on-state resistance	$V_{GS} = 10\text{V}, I_D = 2.5\text{A}$		2.25	2.8	$\Omega$	
$V_{GS(TH)}$	Gate threshold voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	3		5	V	
$g_{fs}$	Forward transconductance	$V_{DS} = 50\text{V}, I_D = 2.5\text{A}$ (Note 1)		4.0		S	
◎ DYNAMIC CHARACTERISTICS							
$C_{ISS}$	Input capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		1200	1550	pF	
$C_{OSS}$	Output capacitance				110		145
$C_{RSS}$	Reverse transfer capacitance				15		20
◎ SWITCHING CHARACTERISTICS							
$t_{d(ON)}$	Turn-on delay time	$V_{DD} = 450\text{V}, V_{GS} = 10\text{V}$ $I_D = 5\text{A}, R_{GS} = 25\Omega$ (Note 1,2)		28	65	ns	
$t_r$	Rise time				65		140
$t_{d(OFF)}$	Turn-off delay time				65		140
$t_f$	Fall time				50		110
$Q_G$	Total gate charge	$V_{DD} = 720\text{V}, V_{GS} = 10\text{V}$ $I_D = 5\text{A},$ (Note 1,2)		31	40	nC	
$Q_{GS}$	Gate to source charge				7.2		
$Q_{GD}$	Gate to drain charge (Miller charge)				15		

SOURCE TO DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{SD}$	Diode forward voltage	$I_{SD} = 5\text{A}, V_{GS} = 0\text{V}$			1.4	V
$I_S$ (Isd)	Continuous source to drain current	Integral reverse P-N junction diode in the MOSFET 			5	A
$I_{SM}$	Pulsed source current				12	
$t_{rr}$	Reverse recovery time	$I_{SD} = 5.4\text{A}, V_{GS} = 0\text{V},$ $di_f/dt = 100\text{A}/\mu\text{s}$		610		ns
$Q_{rr}$	Reverse recovery charge			5.30		$\mu\text{C}$

Note: 1. Pulse test: Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .  
2. Essentially independent of operating temperature.

### ORDERING INFORMATION SCHEME



### ■ TEST CIRCUITS AND WAVEFORMS

Fig.1A Peak diode recovery dv/dt test circuit

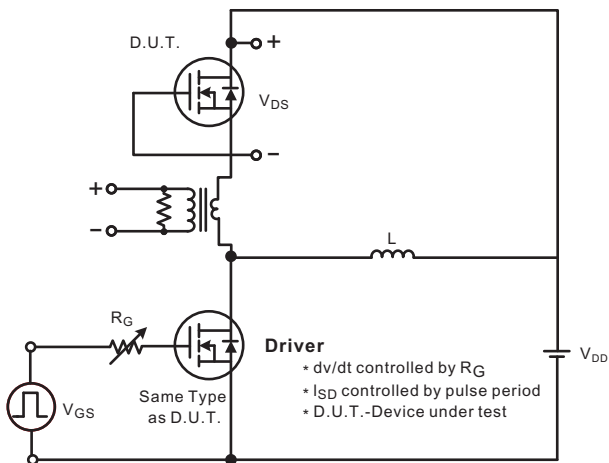
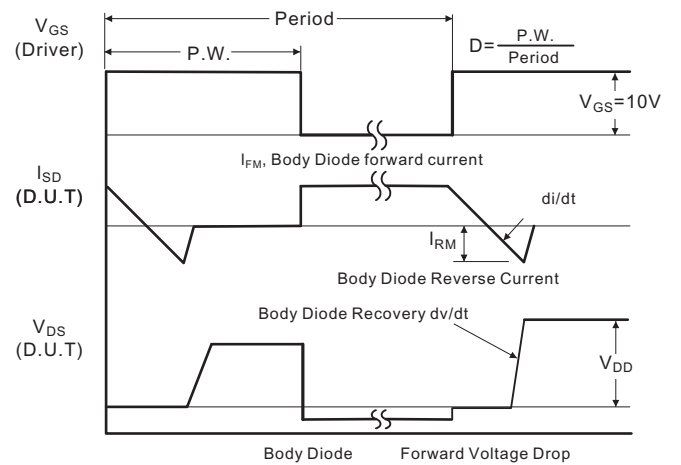


Fig.1B Peak diode recovery dv/dt waveforms



## TEST CIRCUITS AND WAVEFORMS (Cont.)

Fig.2A Switching test circuit

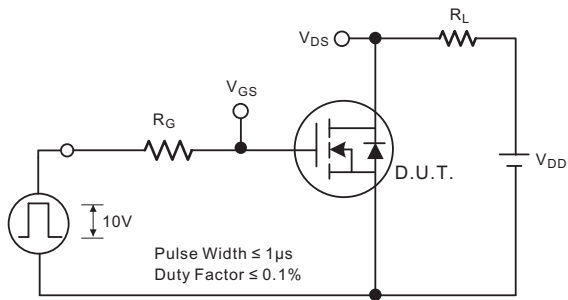


Fig.2B Switching Waveforms

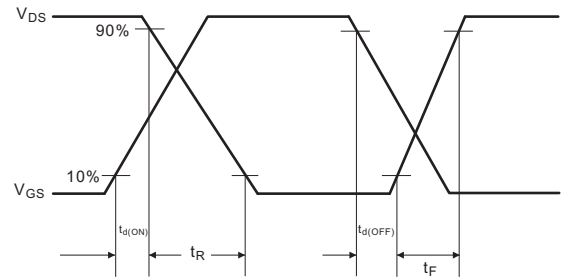


Fig.3A Gate charge test circuit

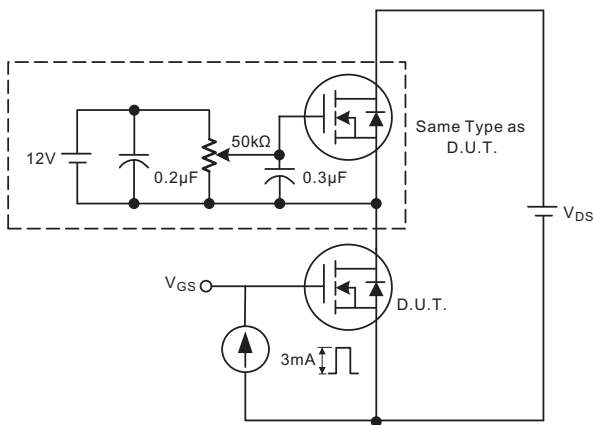


Fig.3B Gate charge waveform

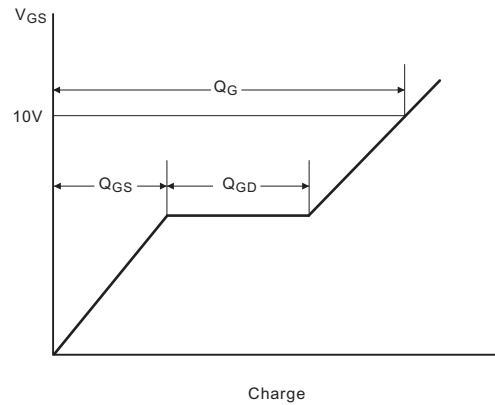


Fig.4A Unclamped Inductive switching test circuit

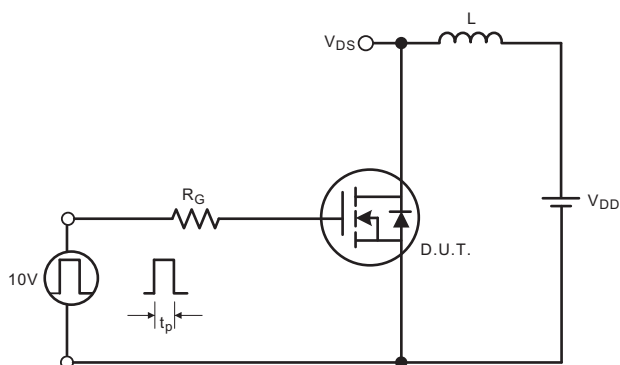
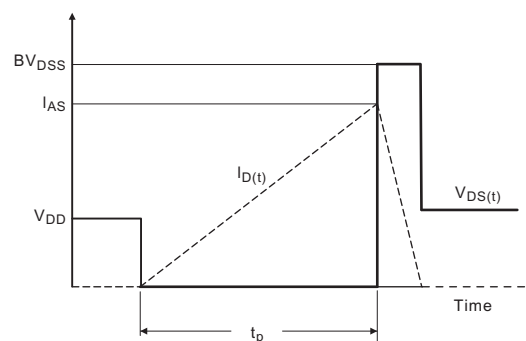
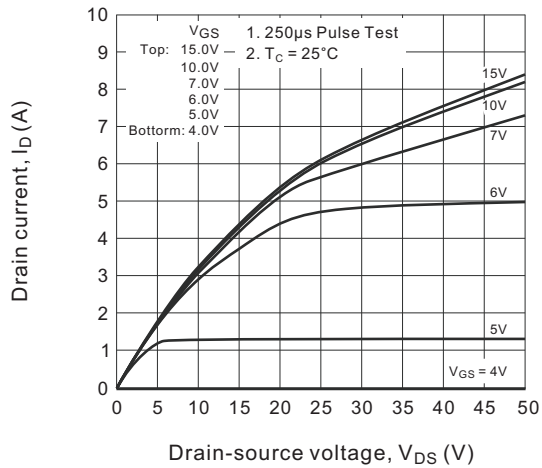


Fig.4B Unclamped Inductive switching waveforms

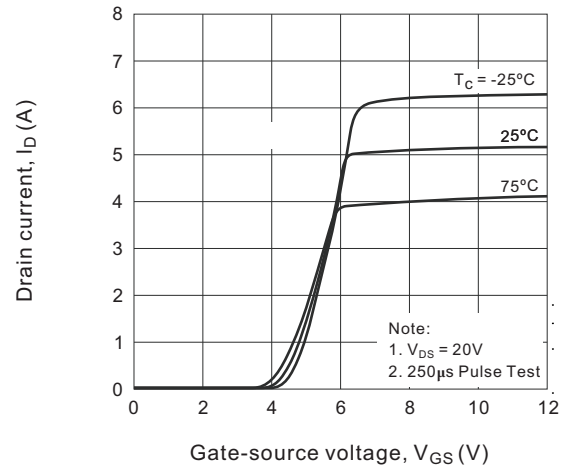


### ■ TYPICAL CHARACTERISTICS

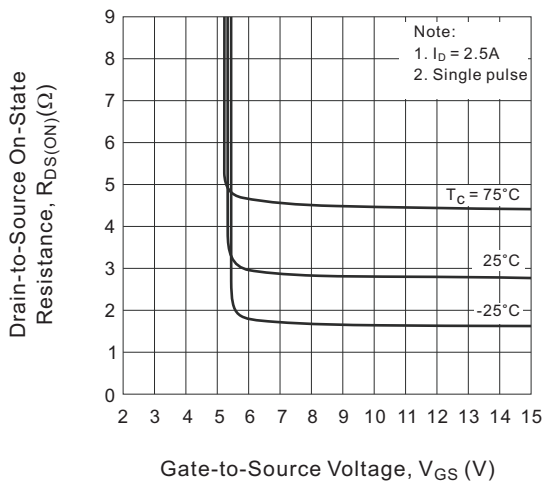
**Fig.1 On-State characteristics**



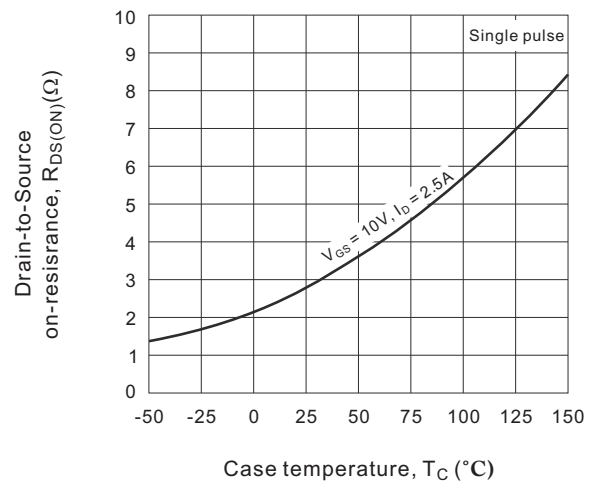
**Fig.2 Transfer characteristics**



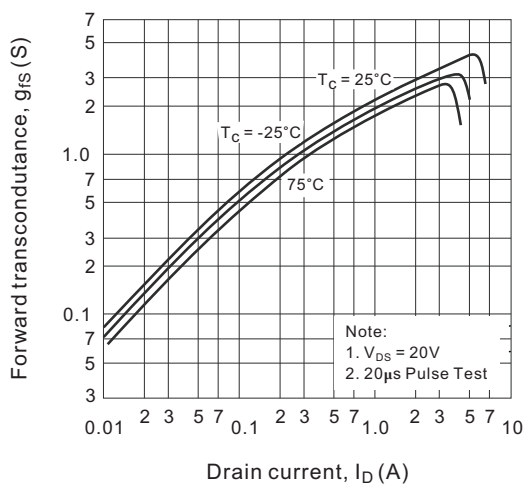
**Fig.3 On-Resistance variation vs. Gate voltage**



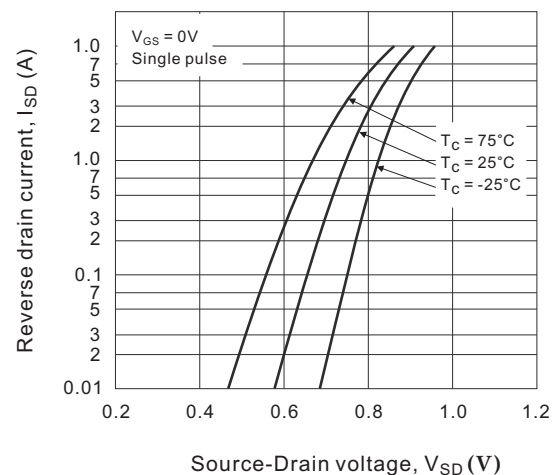
**Fig.4 On-State resistance vs. Case temperature**



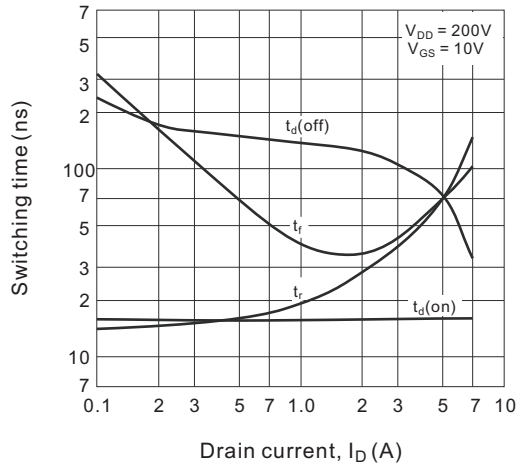
**Fig.5 Typical forward transconductance**



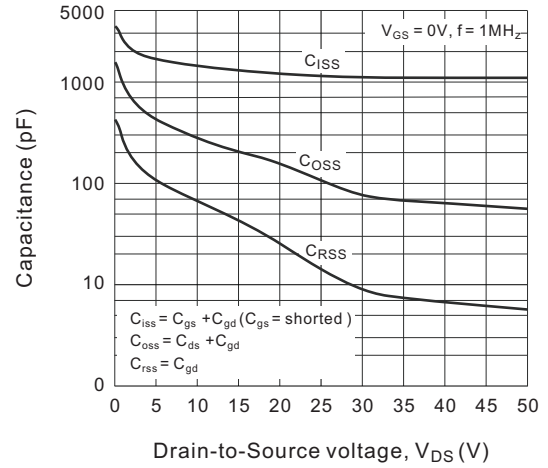
**Fig.6 Typical source-drain diode forward voltage**



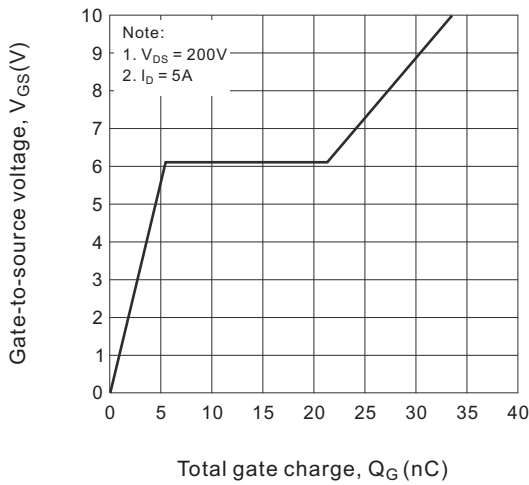
**Fig.7 Switching time vs. Drain current**



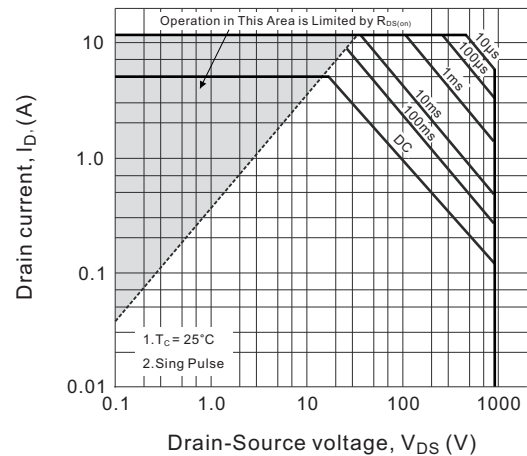
**Fig.8 Typical capacitance vs. Drain-Source voltage**



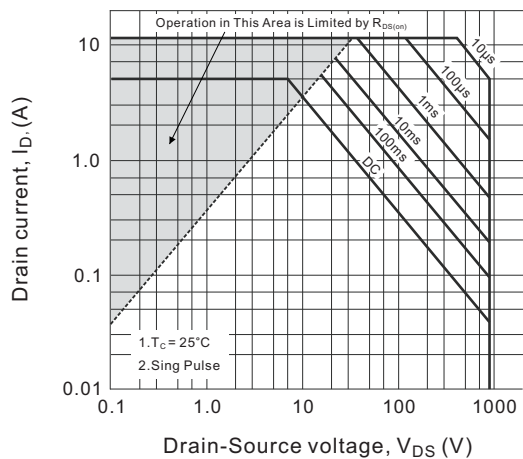
**Fig.9 Typical gate charge vs. Gate-Source voltage**



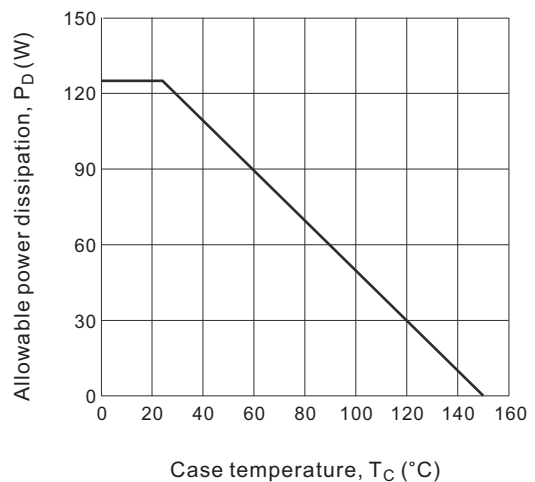
**Fig.10-1 Maximum safe operating area for 5N90A**



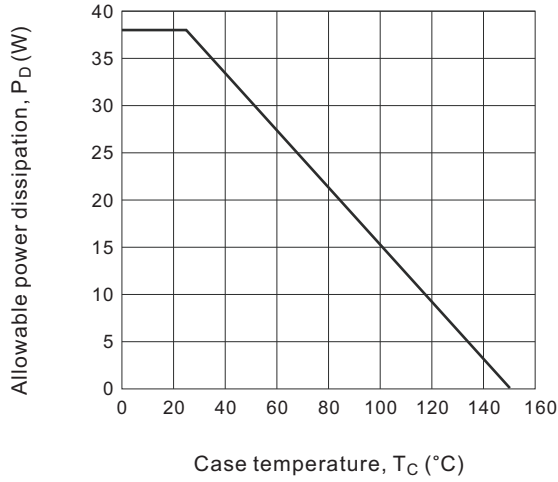
**Fig.10-2 Maximum safe operating area for 5N90AF**



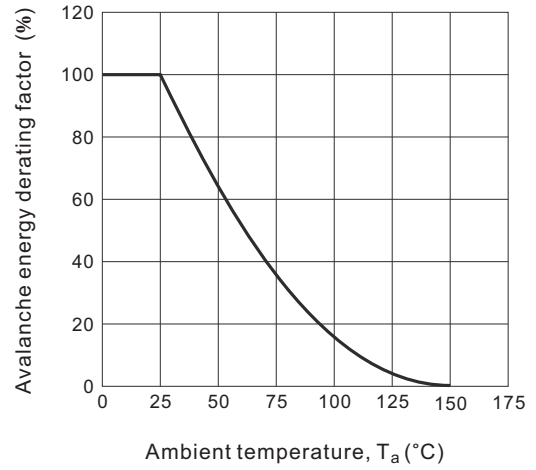
**Fig.11 Power dissipation vs. Case temperature for 5N90A**



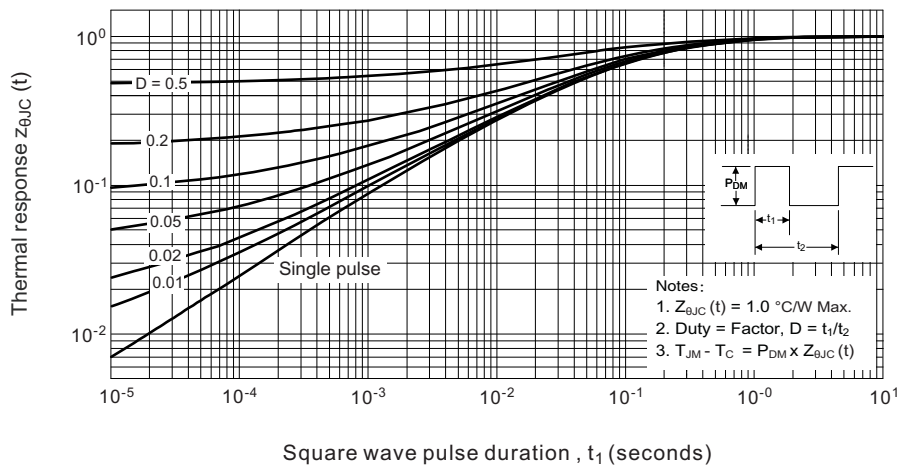
**Fig.12 Power dissipation vs. Case temperature for 5N90AF**



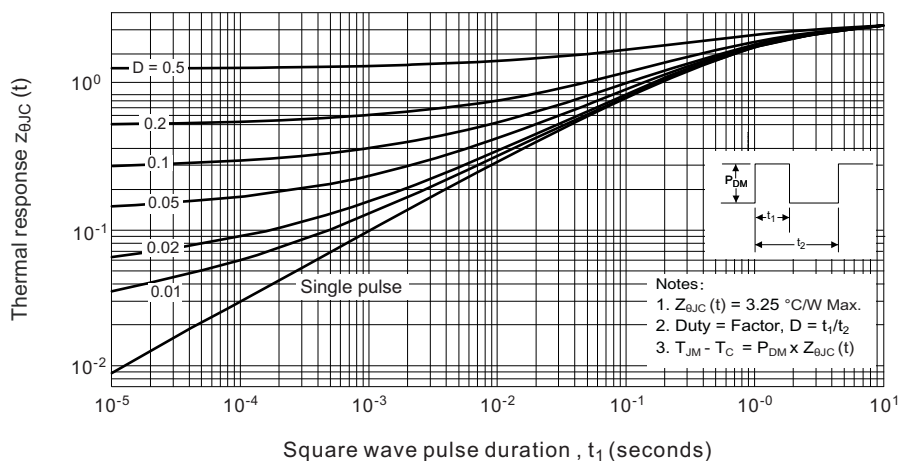
**Fig.13 Avalanche energy derating factor vs. Ambient temperature**



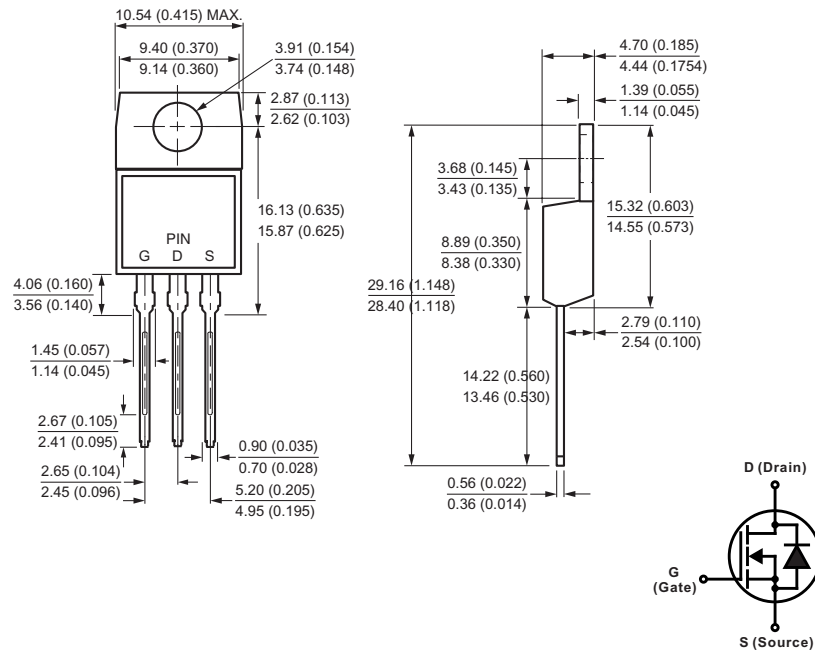
**Fig.14-1 Transient thermal response curve for 5N90A**



**Fig.14-2 Transient thermal response curve for 5N90AF**

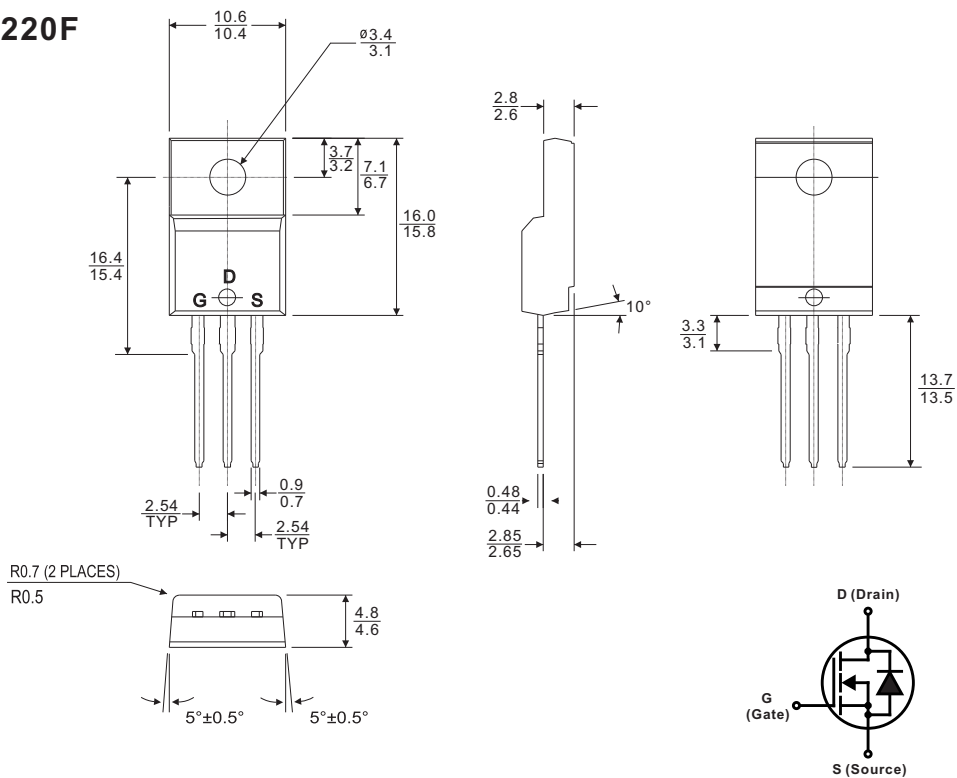


**TO-220AB**



All dimensions in millimeters(inches)

**TO-220F**



All dimensions in millimeters